

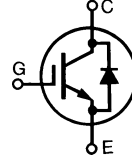
# IGBT with Diode PLUS247™ package

# IXSK 40N60BD1 IXSX 40N60BD1

Short Circuit SOA Capability

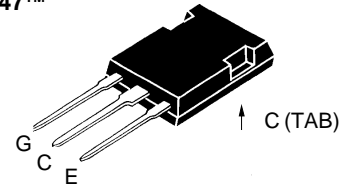
$V_{CES} = 600 \text{ V}$   
 $I_{C25} = 75 \text{ A}$   
 $V_{CE(sat)} = 2.2 \text{ V}$   
 $t_{fi(typ)} = 120 \text{ ns}$

Preliminary data

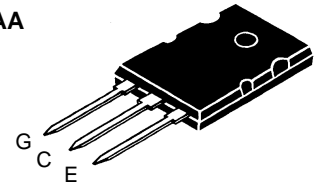


Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	600	V
$V_{CGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GE} = 1 \text{ M}\Omega$	600	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$ , limited by leads	75	A
$I_{C90}$	$T_C = 90^\circ\text{C}$	40	A
$I_{CM}$	$T_C = 25^\circ\text{C}$ , 1 ms	150	A
<b>SSOA</b> <b>(RBSOA)</b>	$V_{GE} = 15 \text{ V}$ , $T_{VJ} = 125^\circ\text{C}$ , $R_G = 22 \Omega$ Clamped inductive load, $L = 30 \mu\text{H}$	$I_{CM} = 80$ @ $0.8 V_{CES}$	A
$t_{SC}$ <b>(SCSOA)</b>	$V_{GE} = 15 \text{ V}$ , $V_{CE} = 360 \text{ V}$ , $T_J = 125^\circ\text{C}$ $R_G = 22 \Omega$ , non repetitive	10	$\mu\text{s}$
$P_C$	$T_C = 25^\circ\text{C}$	280	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$M_d$	Mounting torque (TO-264)	0.9/6	Nm/lb.in.
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$
<b>Weight</b>	TO-264	10	g
	PLUS247	5	g

PLUS 247™  
(IXSX)



TO-264 AA  
(IXSK)



G = Gate, C = Collector,  
E = Emitter

### Features

- International standard packages
- Guaranteed Short Circuit SOA capability
- Medium frequency IGBT and anti-parallel FRED in one package
- Latest generation HDMOS™ process
- Low  $V_{CE(sat)}$  - for minimum on-state conduction losses
- MOS Gate turn-on - drive simplicity
- Fast Recovery, low leakage Epitaxial Diode - soft recovery with low  $I_{RM}$

### Applications

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

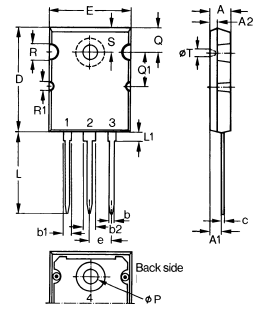
### Advantages

- PLUS 247™ package for clip or spring mounting
- Space savings (two devices in one package)
- Reduces assembly time and cost

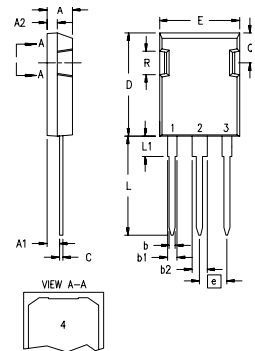
Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$BV_{CES}$	$I_C = 1 \text{ mA}$ , $V_{GE} = 0 \text{ V}$	600		V
$V_{GE(th)}$	$I_C = 4 \text{ mA}$ , $V_{CE} = V_{GE}$	4		V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$		650 $\mu\text{A}$
		$T_J = 150^\circ\text{C}$		5 mA
$I_{GES}$	$V_{CE} = 0 \text{ V}$ , $V_{GE} = \pm 20 \text{ V}$			$\pm 100 \text{ nA}$
$V_{CE(sat)}$	$I_C = I_{C90}$ , $V_{GE} = 15 \text{ V}$			2.2 V

Symbol	Test Conditions	Characteristic Values			
		(T <sub>J</sub> = 25°C, unless otherwise specified)			
		min.	typ.	max.	
<b>g<sub>fs</sub></b>	I <sub>C</sub> = I <sub>C90</sub> ; V <sub>CE</sub> = 10 V, Pulse test, t ≤ 300 μs, duty cycle ≤ 2 %	16	23	S	
<b>C<sub>iss</sub></b>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		3700	pF	
<b>C<sub>oss</sub></b>			440	pF	
<b>C<sub>rss</sub></b>			60	pF	
<b>Q<sub>g</sub></b>	I <sub>C</sub> = I <sub>C90</sub> , V <sub>GE</sub> = 15 V, V <sub>CE</sub> = 0.5 V <sub>CES</sub>		190	nC	
<b>Q<sub>ge</sub></b>			45	nC	
<b>Q<sub>gc</sub></b>			88	nC	
<b>t<sub>d(on)</sub></b>	<b>Inductive load, T<sub>J</sub> = 25°C</b> I <sub>C</sub> = I <sub>C90</sub> , V <sub>GE</sub> = 15 V, L = 100 μH, V <sub>CE</sub> = 0.8 V <sub>CES</sub> , R <sub>G</sub> = 2.7 Ω Remarks: Switching times may increase for V <sub>CE</sub> (Clamp) > 0.8 • V <sub>CES</sub> , higher T <sub>J</sub> or increased R <sub>G</sub>		50	ns	
<b>t<sub>ri</sub></b>			50	ns	
<b>t<sub>d(off)</sub></b>			110	200	ns
<b>t<sub>fi</sub></b>			120	200	ns
<b>E<sub>off</sub></b>			1.8	2.6	mJ
<b>t<sub>d(on)</sub></b>	<b>Inductive load, T<sub>J</sub> = 125°C</b> I <sub>C</sub> = I <sub>C90</sub> , V <sub>GE</sub> = 15 V, L = 100 μH V <sub>CE</sub> = 0.8 V <sub>CES</sub> , R <sub>G</sub> = 2.7 Ω Remarks: Switching times may increase for V <sub>CE</sub> (Clamp) > 0.8 • V <sub>CES</sub> , higher T <sub>J</sub> or increased R <sub>G</sub>		50	ns	
<b>t<sub>ri</sub></b>			50	ns	
<b>E<sub>on</sub></b>			2.2	mJ	
<b>t<sub>d(off)</sub></b>			190	ns	
<b>t<sub>fi</sub></b>			180	ns	
<b>E<sub>off</sub></b>			2.6	mJ	
<b>R<sub>thJC</sub></b>				0.48 K/W	
<b>R<sub>thCK</sub></b>			0.15	K/W	

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C, unless otherwise specified)		
		min.	typ.	max.
<b>V<sub>F</sub></b>	I <sub>F</sub> = I <sub>C90</sub> ; V <sub>GE</sub> = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			1.8 V
<b>I<sub>RM</sub></b>	I <sub>F</sub> = I <sub>C90</sub> ; V <sub>GE</sub> = 0 V, -di <sub>F</sub> /dt = 100 A/μs V <sub>R</sub> = 100 V		2	2.5 A
<b>t<sub>rr</sub></b>		I <sub>F</sub> = 1 A; -di <sub>F</sub> /dt = 200 A/μs; V <sub>R</sub> = 30 V		35
<b>R<sub>thJC</sub></b>				0.75 K/W

**TO-264 AA Outline**


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.82	5.13	.190	.202
A1	2.54	2.89	.100	.114
A2	2.00	2.10	.079	.083
b	1.12	1.42	.044	.056
b1	2.39	2.69	.094	.106
b2	2.90	3.09	.114	.122
c	0.53	0.83	.021	.033
D	25.91	26.16	1.020	1.030
E	19.81	19.96	.780	.786
e	5.46 BSC		.215 BSC	
J	0.00	0.25	.000	.010
K	0.00	0.25	.000	.010
L	20.32	20.83	.800	.820
L1	2.29	2.59	.090	.102
P	3.17	3.66	.125	.144
Q	6.07	6.27	.239	.247
Q1	8.38	8.69	.330	.342
R	3.81	4.32	.150	.170
R1	1.78	2.29	.070	.090
S	6.04	6.30	.238	.248
T	1.57	1.83	.062	.072

**PLUS247™ (IXSX)**


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.83	5.21	.190	.205
A <sub>1</sub>	2.29	2.54	.090	.100
A <sub>2</sub>	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b <sub>1</sub>	1.91	2.13	.075	.084
b <sub>2</sub>	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190